

# Maxence Bouvier, PhD

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AI & HW Research Scientist with 8+ years of experience in ML and Chip Design. Currently building LLM-driven circuit design automation at Arago (AIME team). Expertise spans LLM-based EDA automation, analog/digital circuit optimization, Bayesian design space exploration, energy-efficient HW accelerators, and ML infrastructure tooling.

## EXPERIENCE

### Arago

AI for Chip Design

Paris, France

Nov 2025 - Present

#### o LLM-Driven Circuit Design Automation (AIME)

- \* Built **circuit\_explorer**: FunSearch-inspired LLM exploration engine for analog/digital circuits. LLM generates Python circuit constructors, evaluated via ngspice/Optuna two-stage optimization. Supports Claude, OpenAI, HuggingFace, and local llama.cpp backends.
- \* Developed **virtuoso\_adapter**: Python automation framework for Cadence Virtuoso with bidirectional SKILL bridge. Enables automated ADC characterization (ENOB/SFDR/SNR), waveform analysis (PSF to NumPy), and remote Spectre simulation.
- \* Created **ngspice\_playground**: Docker-based EDA environments with analog (NGSPICE + SKY130 PDK) and digital (Yosys + OpenROAD + ASAP7) toolchains, GPU-accelerated ML, and CI/CD automation.

#### o Memory Configuration Optimization

Developed **memcfg\_opt**: Bayesian optimization tool (Optuna) for ARM SRAM design. Multi-objective optimization (area, timing, power), 10-100x faster than grid search, with 1027+ tests and 95% coverage.

#### o AI/ML Infrastructure & Tooling

- \* Built **hf\_quantizer**: CLI tool for 4-bit model quantization using SING (Sinkhorn-Normalized Quantization) with automated HuggingFace Hub deployment and HumanEval verification.
- \* Created **mcp\_kiwi**: Model Context Protocol server connecting Claude to internal wiki (Outline), with LRU caching, rate limiting, YunoHost SSO, and full document/collection CRUD.
- \* Developed internal Claude Code plugin marketplace for team-wide AI tool distribution and management.

### Huawei

AI & HW Research Scientist

Zurich, Switzerland

May 2024 - Oct 2025

#### o Team Leader

Built and led a multidisciplinary team of experts to develop innovative solutions for reducing switching activity and power consumption in Huawei's GPUs.

#### o ML for Chip Design

- \* Designed and developed an automated ML-based framework for iterative generation of multiplier circuits with reduced switching activity and lower power consumption. The full pipeline was up and running in less than three months, working alone.
- \* Deployed synthesis and simulation of millions of designs using containerized (Docker), open source EDA tools on a multi-node SLURM cluster. Adapted the framework for commercial EDA tools.
- \* Proved that Network Inversion is superior to other state of the art method for design generation (and design space exploration).
- \* Results: we found multiplier encodings that reduce power consumption by approximately 10% compared to conventional two's complement implementations. (*1 paper*.)

#### o ML for Advanced Synthesis

Developed a predictor-driven Logic Synthesis Optimization framework achieving up to 21% QoR improvement and 14 faster execution. - (*2 papers*.)

#### o Characterization of ML Workloads Acceleration

- \* Developed a simulation platform to accurately map (tiling and multi-core scheduling) tensor operations onto Huawei's Ascend "Cube" tensor accelerator.
- \* Exploited the simulator to benchmark tensor reshaping and vector reordering strategies, proposing novel software-level optimizations that effectively reduce power consumption.

#### o Conference Attendance

2025 DAC, 2025 International Conference on LLM-Aided Design (ICLAD).

### SONY

Senior AI Research Engineer

Zurich, Switzerland

Aug 2023 - Apr 2024

#### o Sparsity Exploitation in Transformers

- \* Engineered an asynchronous PointNet-based embedding, enabling continuous spatio-temporal data conversion into dense tensors for seamless, continuous feeding of Transformer models. - (*1 paper, 1 patent*.)
- \* Designed an NPU-compatible, block-wise sparse scaled dot-product attention module for highly efficient flash attention in Transformers, achieving more than 50% FLOPs reduction during inference and higher accuracy.

#### o SLAM Enhanced AI Training

Enhanced performance by incorporating a cutting-edge SLAM pipeline for multi-modal training process, achieving 6x faster model convergence and a 15% accuracy improvement.

AI Research Engineer

June 2022 - Aug 2023

- **SW/HW Co-Design Automation with Neural Architecture Search**
  - \* Built an AI-driven, Hardware-Aware Neural Architecture Search framework. Reduced model FLOP cost to 8% of the original, with only a 4% accuracy loss.
  - \* Integrated a Design Space Exploration software in the NAS loop to estimate energy and latency of model execution.
- **Transformer Hardware Acceleration Survey:** Conducted a literature study, featured in CTO's strategic report.
- **Vision Transformer for Image Generation**
  - \* Implemented an AI model leveraging CNN and Transformer architectures to realize advanced frame generation. - (1 patent.)
  - \* Built a live demo of the model, from image sensor to application. This led to 2 major collaborations with other teams.
  - \* Packaged the model as an API to simplify sharing across teams and projects.
- **Software Maintainer:** Responsible for the CI of a few Python libraries shared among teams.
- **Conference Attendance:** 2023 ISSCC.

## STMicroelectronics

Digital IC Design Engineer

Grenoble, France  
Apr 2021 - May 2022

- **CPU Design and Automation**
  - \* Created a toolbox to automate component assembly of the Trace and Debug subsystem with ARM's Armv9-A SoC modules.
  - \* Developed an RTL generator for STM32 MPU SoC, streamlining the design of a multi-clock-domain reset and clock-control system for over 300 peripherals.
- **CPU Benchmarking:** Conducted CoreMark benchmarking on a multi-core MPU SoC, highlighting significant performance gains (up to 6x) through compiler updates.
- **Conference Attendance:** 2021 ISSCC.

## CEA LETI

Doctoral Researcher on AI and Digital IC Design

Grenoble, France  
Apr 2018 - Apr 2021

- **Neuromorphic Hardware Survey:** Conducted a comprehensive literature review on scalable, distributed, multi-chip neuromorphic hardware, leading to a widely cited publication in ACM JETC. - (1 paper.)
- **ULP NPU Design:** Built (RTL design, synthesis and layout) an ultra-low-power sparse AI accelerator, setting energy efficiency records (2.86pJ/OP in 28nm) and enabling seamless integration for 3D-stacked imagers. - (1 paper, 2 patents.)
- **EB VIO/SLAM Pipeline and Object Detection Innovation:** Developed an Event-Based VIO/SLAM pipeline with ego-motion compensation, leading to a solution for detecting moving objects. - (1 patent.)
- **Conference Attendance:** 2019 ISSCC, 2021 DAC.

## IBM Research

Intern IC Design Engineer

Yorktown Heights, NY, USA  
Feb 2017 - Aug 2017

- Automated wafer-scale memory device characterization, reducing execution time from days to hours.
- Contributed to the optimization of PCM technologies for Compute-in-Memory-based AI acceleration. - (1 paper, 1 patent.)

## SKILLS

- **Languages:** Python, C/C++, SystemVerilog, SKILL, MATLAB, VHDL
- **AI/ML:** PyTorch, Transformers, LLM APIs (Claude, OpenAI), llama.cpp, Optuna, SING, MLFlow, ONNX
- **Hardware & EDA Tools:** NGSPICE, Spectre, Virtuoso, Yosys, OpenROAD, ABC, Mockturtle, Verilator, CocoTB, Design Compiler, PrimeTime
- **Software & DevOps:** Docker, Git, CI/CD, MCP (Model Context Protocol), Claude Code

## EDUCATION

- **Grenoble Alpes University** | Ph.D. in Computer Science Apr 2018 – Apr 2021 | Grenoble, France
- **EPFL** | "M.Eng. in Electronics (Highest Honors)" Sep 2015 – Sep 2017 | Lausanne, Switzerland
- **Grenoble Institute of Technology** | B.Eng. in Electronics Sep 2012 – Sep 2015 | Grenoble, France

## PATENTS

- M. Bouvier, et al., "Apparatus, method, and computer program for processing visual event data," WO2024200170A1, 2024.
- M. Bouvier, A. Valentian, "Observation system and associated observation method," US2023196779A1, 2023.
- F. Carta, et al., "Pulsing synaptic devices based on phase-change memory to increase the linearity in weight update," US11557343B2, 2023.
- M. Bouvier, A. Bige, "Device for compensating for movement of an event sensor, and associated systems and methods," WO2022117535A1, 2022.
- M. Bouvier, A. Valentian, "Device for compensating movement of an event-driven sensor and associated observation system and method," US2022101006A1, 2022.

## PUBLICATIONS

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- M. Bouvier, et al., “**GENIAL: Generative Design Space Exploration via Network Inversion for Low Power Algorithmic Logic Units,**” *Under Review*, 2025.
- F. Arnold, M. Bouvier, et al., “**Explicit Sign-Magnitude Encoders Enable Power-Efficient Multipliers,**” *International Workshop on Logic and Synthesis*, 2025.
- F. Arnold\*, M. Bouvier\*, et al., “**The Art of Beating the Odds with Predictor-Guided Random Design Space Exploration,**” *62nd ACM/IEEE Design Automation Conference (DAC) (Poster)*, 2025.
- C. M. Turrero, M. Bouvier, et al., “**ALERT-Transformer: Bridging Asynchronous and Synchronous Machine Learning for Real-Time Event-based Spatio-Temporal Data,**” *Proceedings of the 41st ICML*, 2024.
- M. Bouvier, et al., “**Scalable pitch-constrained neural processing unit for 3D integration with event-based imagers,**” *2021 58th ACM/IEEE Design Automation Conference (DAC)*, 2021.
- M. Bouvier, “**Study and design of an energy-efficient perception module combining event-based image sensors and spiking neural network with 3D integration technologies,**” *Ph.D. Dissertation, Université Grenoble Alpes*, 2021.
- M. Bouvier, et al., “**Spiking neural networks hardware implementations and challenges: A survey,**” *ACM Journal on Emerging Technologies in Computing Systems (JETC)*, 2019.
- P. Vivet, et al., “**Advanced 3D technologies and architectures for 3D smart image sensors,**” *2019 Design, Automation & Test in Europe Conference & Exhibition (DATE)*, 2019.